

PARA LIGHT ELECTRONICS CO., LTD. 11F., No. 8, Jiankang Rd., Zhonghe Dist., New Taipei City 235, Taiwan Tel: 886-2-2225-3733 Fax: 886-2-2225-4800 E-mail: para@para.com.tw www.paralighttaiwan.com

DATA SHEET

PART NO.: LT3535UVC-KPC

REV: <u>A / X</u>

CUSTOMER'S APPROVAL: _____ DRAWING NO.: DS-31P-20-0016

DATE: 2020-03-16

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SURFACE MOUNT DEVICE LED

Part No.: LT3535UVC-KPC

REV:A/X

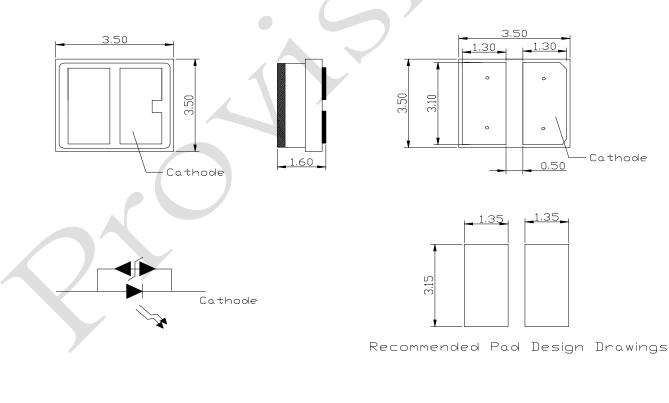
Features

- *SIZE: 3.5*3.5*1.6mm
- *Suitable for all SMT assembly and solder process
- * Available on tape and reel
- * Moisture sensitivity level: Level 3
- * RoHS compliant

Applications

- * Ultraviolet disinfection
- * Phototherapy
- * Bio- Analysis/ Detection
- * General use

Package Dimensions



Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is \pm 0.2mm unless otherwise noted

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■ Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Units	
Power Dissipation	PD	0.5	W	
Forward Current	IF	80	mA	
Peak Forward Current	IFP	150	mA	
Reverse Voltage	VR	5	V	
Operating Temperature	Topr	-40~ +55	Ĉ	
Storage Temperature	Tstg	-40 ~ +80	°C	
Junction Temperature	Tj	90	്റ	

Notes:

1. 1/10 duty cycle o.1 ms pulse width

2. The above forward voltage measurement allowance tolerance is \pm 0.1V

3. ESD<2000V

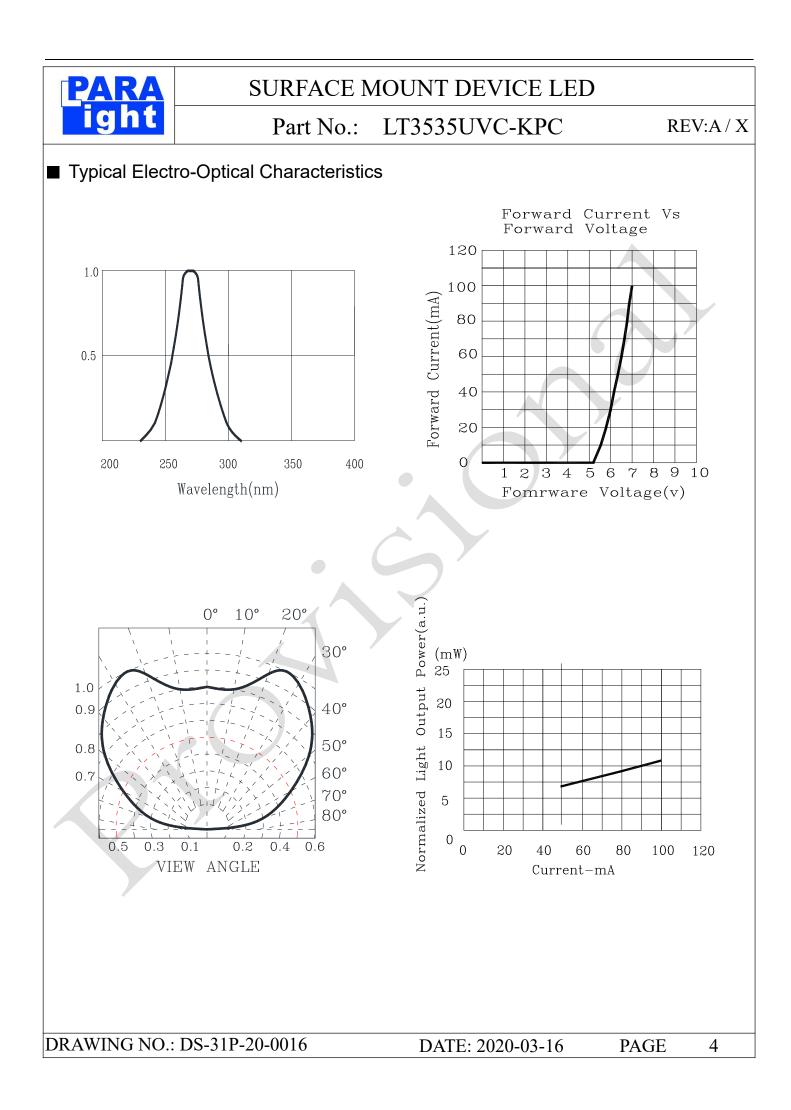
■ ELECTRO-OPTICAL CHARACTERISTICS : (Ta = 25°C)

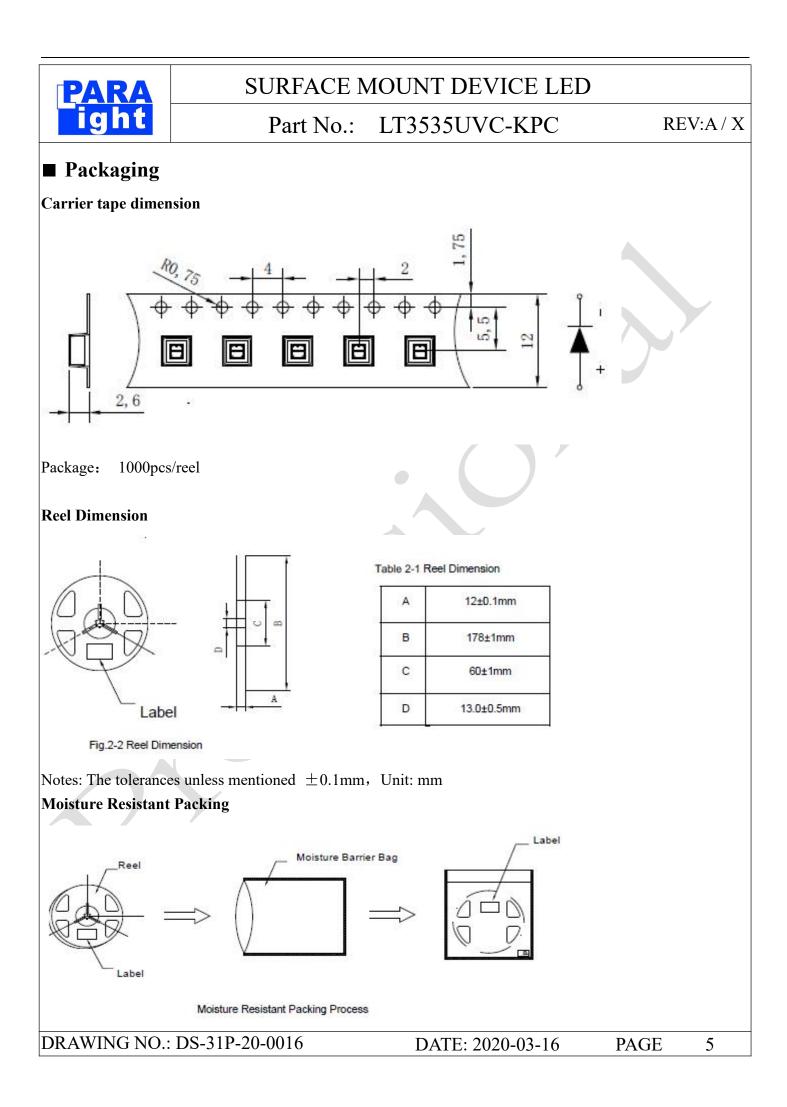
	Parameter	Symbol	TEST	in	Тур	Max.	Unit
	Reverse Current	IR	VR=5V			5	μA
	Forward Voltage	VF	IF=50mA		6.5		V
			IF=50mA		5.8		
	Total Radiant Flux	Φe	IF=80mA		9.2		mW
			IF=100mA		11.5		
	Peak wavelength	λр	IF=50mA		275		nm
	Spectral Line Half - Width	Δλ	IF=50mA		10		nm
	Thermal Resistance	Rthj-s	IF=50mA		45		°C/W
	Half Intensity Angle	201/2	IF=50mA		120		deg

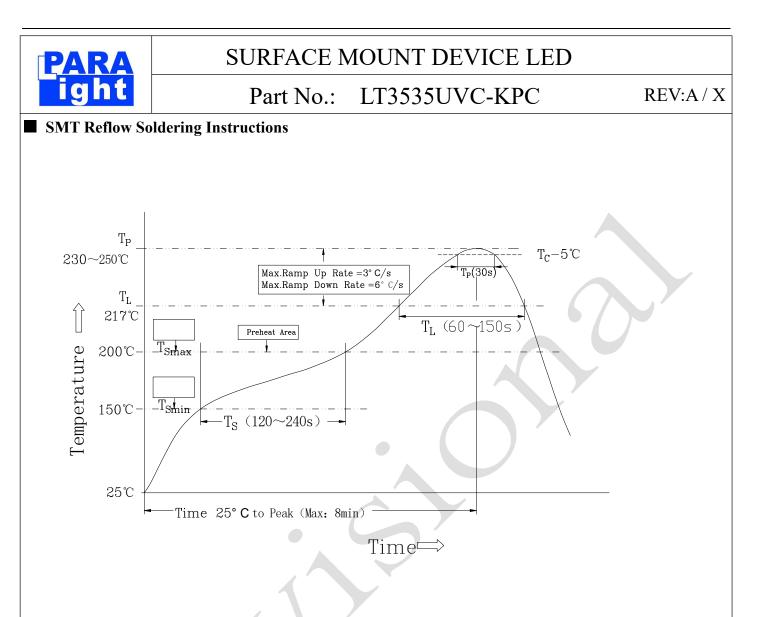
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Notes:

- 1. Reflow soldering should not be done more than two times. If more than 24 hours between the two soldering, LED will be damaged.
- 2. When soldering, do not put stress on the LEDS during heating.

Soldering ron

- 1. When do soldering by hand, keep the temperature of iron below less 300C less than 3 seconds.
- 2. Soldering by hand should be done only one time.

Repairing

Repairing should not be done after the LEDS have been soldered. When repairing is unavoidable, suitable tools must be used.

It should be confirmed in advance whether the characteristics of LEDS will or not be damaged by repairing.



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Cautions

1. The encapsulated material of the LEDS is silicone. Therefore the LEDS have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDS. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper.

2. Components should not be mounted on warped(non co plane)portion of PCB.After soldering,do not warp the circuit board.

3. Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

Handling Precautions

Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

Conditions Temperature Humidity Time Before Opening Aluminum Bag ≤30°C ≤75% Within 1 Year From Date Storage ≤30°C ≤60% 24hours After Opening Aluminum Bag 60±5°C Baking ≥24hours

Storage

Notes

1. If the moisture absorbent material(silica gel) has faded away or the LEDS have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition(65 ± 5)[°]C for above 24 hours.

2. If the package is flatulence or damaged, please notify the sales staff to assist.

3. Similar to most Solid state devices; LEDS are sensitive to Electric-Static Discharge(ESD) and Electrical Over Stress(EOS).

